What is claimed is:

1. A vacuum debris removal system for an integrated circuit manufacturing device, comprising:

a plate;

an slit formed in the plate;

a pair of vacuum tubes, one disposed on each side of the slit; and

a single opening formed in each of the vacuum tubes at a selected location.

2. The vacuum debris removal system of claim 1, wherein the selected location of each single opening is at about a mid-point of the slit.

3. The vacuum debris removal system of claim 1, wherein the selected location of each single opening is in a side of each vacuum tube facing the slit.

4. The vacuum debris removal system of claim 1, wherein each single opening has a predetermined size and shape.

5. The vacuum debris removal system of claim 4, wherein each single opening has a length of about 0.060 inches and a width of about 0.030 inches.

6. The vacuum debris removal system of claim 1, wherein the slit is substantially rectangular and the pair of vacuum tubes extend substantially parallel to each longest side of the slit to at least about a mid-point of the slit.

7. The vacuum debris removal system of claim 1, wherein the slit is elongate and the vacuum tubes extend respectively parallel to each longest side of the slit.

8. The vacuum debris removal system of claim 1, wherein the selected location of each opening causes air flow in the slit to a central location.

9. The vacuum debris removal system of claim 1, wherein the selected location of each opening causes air flow in the slit away from an element of an integrated circuit manufacturing device.

10. The vacuum debris removal system of claim 1, wherein the selected location of the openings causes a maximum reduction of outgassed particles from a resist material contaminating a lens element of an integrated circuit manufacturing device.

11. The vacuum debris removal system of claim 1, wherein the selected location of the openings causes air flow in the slit for dual withdrawal of particles away from an element of an integrated circuit manufacturing device.

12. The vacuum debris removal system of claim 1, wherein each vacuum tube of the pair of vacuum tubes draws between about 3.5 and about 7 cubic feet per hour of air.

13. A vacuum debris removal system for an integrated circuit manufacturing device, comprising:

at least one vacuum tube; and

an opening formed in the at least one vacuum tube at a selected location to cause air flow away from an element of the integrated circuit manufacturing device.

14. The vacuum debris removal system of claim 13, wherein the opening has a predetermined size and shape.

15. The vacuum debris removal system of claim 14, wherein the opening has a length of about 0.060 inches and a width of about 0.030 inches.

16. The vacuum debris removal system of claim 13, wherein the selected location of the opening causes a maximum reduction of outgassed particles from contaminating a lens element of the integrated circuit manufacturing device.

17. The vacuum debris removal system of claim 13, wherein the selected location of the opening is at a mid-point of an exposure slit of the integrated circuit manufacturing device.

18. An apparatus for manufacturing a semiconductor device, comprising:

a stage to hold a semiconductor wafer during processing;

an exposure slit positioned relative to the stage;

projection optics to focus a light beam through the exposure slit and onto a selected portion of the semiconductor wafer;

at least one vacuum tube adjacent the exposure slit; and

a single opening formed in the vacuum tube at a selected location to cause air flow in the exposure slit away from a lens of the projection optics.

19. The apparatus of claim 18, wherein the selected location of the single opening is at about a mid-point of the exposure slit.

20. The apparatus of claim 18, wherein the single opening has a predetermined size and shape.

21. The apparatus of claim 18, further comprising

a second vacuum tube adjacent the exposure slit on an opposite side of the exposure slit from the at least one vacuum tube; and

a single opening formed in the second vacuum tube at a selected location.

22. The apparatus of claim 21, wherein the selected location of each single opening is at about a mid-point of the exposure slit.

23. The apparatus of claim 21, wherein the selected location of the single openings causes a maximum reduction of outgassed particles from contaminating the lens.

24. A method of making a vacuum debris removal system, comprising:

providing at least one vacuum tube; and

forming a single opening in the at least one vacuum tube at a selected location to cause air flow away from an element of an integrated circuit manufacturing device.

25. The method of claim 24, further comprising forming the single opening to have a predetermined size and shape.

26. The method of claim 24, further comprising selecting the location to form the single opening to be at about a mid-point of an exposure slit of the integrated circuit manufacturing device.

27. The method of claim 24, further comprising:

disposing the at least one vacuum tube on one side of an exposure slit of the integrated circuit manufacturing device;

disposing a second vacuum tube on an opposite side of the exposure slit; and

forming a single hole in the second vacuum tube to cause air flow in the exposure slit away from the element of the integrated circuit manufacturing device.

28. A method of removing debris, comprising:

disposing at least one vacuum tube adjacent an exposure slit of an integrated circuit manufacturing device; and

forming a single opening in the at least one vacuum tube at a selected location.

29. The method of claim 28, further comprising forming the single opening to have a predetermined size and shape.

30. The method of claim 28, further comprising selecting the location to form the single opening to be at about a mid-point of the exposure slit.

31. The method of claim 28, further comprising:

disposing a second vacuum tube on an opposite side of the exposure slit from the at one least vacuum tube; and

forming a single hole in the second vacuum tube to cause air flow in the exposure slit away from a lens element of the integrated circuit manufacturing device.